

Amendments to the Claims:

Following is a complete listing of the claims pending in the application, as amended:

1-37. (Canceled)

38. (Currently Amended) A packaged microelectronic device, comprising:
a microelectronic die having an integrated circuit and a plurality of bond-pads coupled to the integrated circuit;

an interposer substrate having a first side coupled to the die, a second side opposite the first side, the interposer substrate having a plurality of ball-pads arranged on the second side to be coupled to a printed circuit board, interconnects electrically coupled to the bond-pads on the die and the ball-pads, and a solder-mask on the second side having openings over the ball-pads;

a plurality of solder-balls arranged so that each solder-ball is in an opening in the solder-mask and contacting a corresponding ball-pad; and

a dielectric compound in the openings in the solder-mask, wherein the dielectric compound surrounds a perimeter portion of the perimeter of each of the ball-pads and the solder-balls.

39. (Original) The device of claim 38 wherein the dielectric compound includes a dielectric flux.

40. (Currently Amended) A packaged microelectronic device, comprising:
a microelectronic die having an integrated circuit and at least one bond-pad coupled to the integrated circuit;

an interposer substrate having a first side coupled to the die, a second side opposite the first side, the interposer substrate having at least one a ball-pad on the second side, an interconnect electrically coupled to the bond-pad on the die and the

| ball-pad, a trace line adjacent to the ball-pad, and a solder-mask on the second side
having an opening over the ball-pad;
 a solder-ball on the ball-pad; and
 a dielectric compound in the opening in the solder-mask that electrically insulates
the ball-pad and the solder-ball from any exposed portion of the adjacent trace line in
the opening.

41. (Original) The device of claim 40 wherein the dielectric compound includes a dielectric flux.

42. (Original) The device of claim 40, further comprising a circuit board having a contact coupled to the solder-ball.

43. (Original) The device of claim 42, further comprising a eutectic paste proximate to the contact.

44. (Original) The device of claim 40, further comprising a eutectic paste proximate to the solder-ball.

45. (Original) The device of claim 40 wherein the dielectric compound in the opening covers an exposed portion of the adjacent trace line.